

Appl. No. 10/628,881  
Amdt. Dated January 4, 2006  
Reply to Office Action of October 5, 2005

Attorney Docket No. 81872.0049  
Customer No.: 26021

**Amendments to the Specification:**

Please replace the paragraph beginning at page 32, line 19, with the following rewritten paragraph:

The present inventors used six kinds of substrate materials for the base substrate 2 whose thermal expansion coefficients were within the range of 7-25 ppm/°C The material used for the solder was ~~An-Ag-Cu~~ Sn-Ag-Cu based solder. By ~~seting~~ setting the sealing width, for example, to 200µm, the present inventors investigated relationship between the amount of plastic strain of the base substrate and mean time to failure. The amount of plastic strain refers to the ratio of strain at one side of the base substrate 2 to the thickness of the substrate while the base substrate 2 is joined to the surface acoustic wave element 1. The mean time to failure was obtained from the average number of occurrences of failure resulted from the repetition of a cycle -40°C to 125°C for 30 minutes.